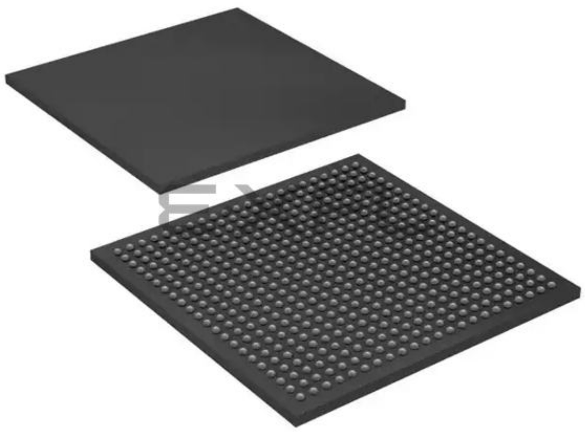

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	2475
Number of Logic Elements/Cells	39600
Total RAM Bits	1161216
Number of I/O	328
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce40f23c9ln

Clocking Modes

Cyclone IV devices M9K memory blocks support the following clocking modes:

- Independent
- Input or output
- Read or write
- Single-clock

When using read or write clock mode, if you perform a simultaneous read or write to the same address location, the output read data is unknown. If you require the output data to be a known value, use either single-clock mode or I/O clock mode and choose the appropriate read-during-write behavior in the MegaWizard Plug-In Manager.

☞ Violating the setup or hold time on the memory block input registers might corrupt the memory contents. This applies to both read and write operations.

☞ Asynchronous clears are available on read address registers, output registers, and output latches only.

Table 3–5 lists the clocking mode versus memory mode support matrix.

Table 3–5. Cyclone IV Devices Memory Clock Modes

Clocking Mode	True Dual-Port Mode	Simple Dual-Port Mode	Single-Port Mode	ROM Mode	FIFO Mode
Independent	✓	—	—	✓	—
Input or output	✓	✓	✓	✓	—
Read or write	—	✓	—	—	✓
Single-clock	✓	✓	✓	✓	✓

Independent Clock Mode

Cyclone IV devices M9K memory blocks can implement independent clock mode for true dual-port memories. In this mode, a separate clock is available for each port (port A and port B). `clock A` controls all registers on the port A side, while `clock B` controls all registers on the port B side. Each port also supports independent clock enables for port A and B registers.

Input or Output Clock Mode

Cyclone IV devices M9K memory blocks can implement input or output clock mode for FIFO, single-port, true, and simple dual-port memories. In this mode, an input clock controls all input registers to the memory block including data, address, `byteena`, `wren`, and `rden` registers. An output clock controls the data-output registers. Each memory block port also supports independent clock enables for input and output registers.

Table 5–5. Cyclone IV GX PLL Features (Part 2 of 2)

Features	Availability									
	General Purpose PLLs				Multipurpose PLLs					
	PLL_1 *(1), (10)*	PLL_2 *(1), (10)*	PLL_3 *(2)*	PLL_4 *(3)*	PLL_1 *(4)*	PLL_2 *(4)*	PLL_5 *(1), (10)*	PLL_6 *(1), (10)*	PLL_7 *(1)*	PLL_8 *(1)*
Input clock switchover	✓									
User mode reconfiguration	✓									
Loss of lock detection	✓									
PLL drives TX Serial Clock, TX Load Enable, and TX Parallel Clock	✓	✓	—	—	✓					
VCO output drives RX clock data recovery (CDR) clock	—				✓					
PLL drives `FREF` for ppm detect	✓	✓	—	—	✓					

Notes to Table 5–5:

(1) This is only applicable to EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices in F672 and F896 package.
(2) This is applicable to all Cyclone IV devices.
(3) This is applicable to all Cyclone IV devices except EP4CGX15 devices in all packages, EP4CGX22, and EP4CGX30 devices in F169 package.
(4) This is only applicable to EP4CGX15, EP4CGX22, and all EP4CGX30 devices except EP4CGX30 in the F484 package..
(5) C counters range from 1 through 512 if the output clock uses a 50% duty cycle. For any output clocks using a non-50% duty cycle, the post-scale counters range from 1 through 256.
(6) These clock pins can access the GCLK networks.
(7) These clock pins are only available in EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices and cannot access the GCLK networks. `CLK[17,19,20,21]p` can be used as single-ended clock input pins.
(8) Only applicable if the input clock jitter is in the input jitter tolerance specifications.
(9) The smallest phase shift is determined by the voltage-controlled oscillator (VCO) period divided by eight. For degree increments, Cyclone IV GX devices can shift all output frequencies in increments of at least 45°. Smaller degree increments are possible depending on the frequency and divide parameters.
(10) This is applicable to the EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices in F484 package.

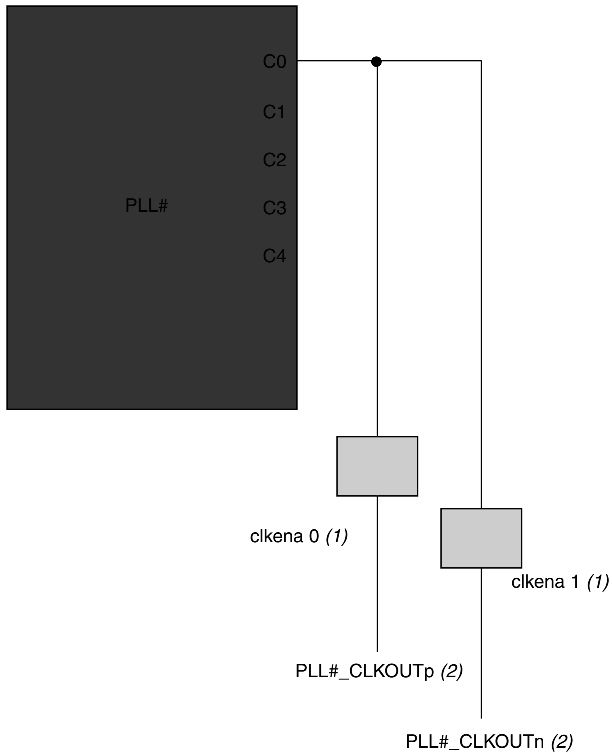
Table 5–6 lists the features available in Cyclone IV E PLLs.

Table 5–6. Cyclone IV E PLL Features (Part 1 of 2)

Hardware Features	Availability
C (output counters)	5
M, N, C counter sizes	1 to 512 *(1)*
Dedicated clock outputs	1 single-ended or 1 differential pair
Clock input pins	4 single-ended or 2 differential pairs
Spread-spectrum input clock tracking	✓ *(2)*
PLL cascading	Through GCLK
Compensation modes	Source-Synchronous Mode, No Compensation Mode, Normal Mode, and Zero Delay Buffer Mode
Phase shift resolution	Down to 96-ps increments *(3)*
Programmable duty cycle	✓
Output counter cascading	✓
Input clock switchover	✓
User mode reconfiguration	✓

Figure 5–11 shows the external clock outputs for PLLs.

Figure 5–11. External Clock Outputs for PLLs



Notes to Figure 5–11:

(1) These external clock enable signals are available only when using the ALTCLKCTRL megafunction.

(2) `PLL#_CLKOUTp` and `PLL#_CLKOUTn` pins are dual-purpose I/O pins that you can use as one single-ended clock output or one differential clock output. When using both pins as single-ended I/Os, one of them can be the clock output while the other pin is configured as a regular user I/O.

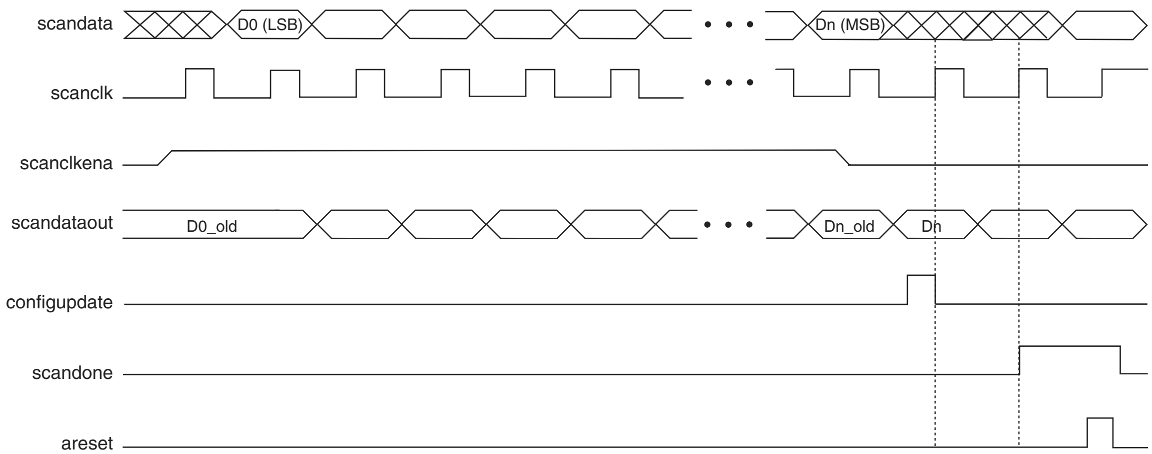
Each pin of a differential output pair is 180° out of phase. The Quartus II software places the NOT gate in your design into the I/O element to implement 180° phase with respect to the other pin in the pair. The clock output pin pairs support the same I/O standards as standard output pins.

To determine which I/O standards are supported by the PLL clock input and output pins, refer to the *Cyclone IV Device I/O Features* chapter.

Cyclone IV PLLs can drive out to any regular I/O pin through the GCLK. You can also use the external clock output pins as GPIO pins if external PLL clocking is not required.

Figure 5–23 shows a functional simulation of the PLL reconfiguration feature.

Figure 5–23. PLL Reconfiguration Scan Chain



When reconfiguring the counter clock frequency, the corresponding counter phase shift settings cannot be reconfigured using the same interface. You can reconfigure phase shifts in real time using the dynamic phase shift reconfiguration interface. If you reconfigure the counter frequency, but wish to keep the same non-zero phase shift setting (for example, 90°) on the clock output, you must reconfigure the phase shift after reconfiguring the counter clock frequency.

Post-Scale Counters (C0 to C4)

You can configure multiply or divide values and duty cycle of post-scale counters in real time. Each counter has an 8-bit high time setting and an 8-bit low time setting. The duty cycle is the ratio of output high or low time to the total cycle time, that is the sum of the two. Additionally, these counters have two control bits, `rbypass`, for bypassing the counter, and `rselodd`, to select the output clock duty cycle.

When the `rbypass` bit is set to 1, it bypasses the counter, resulting in a divide by one. When this bit is set to 0, the PLL computes the effective division of the VCO output frequency based on the high and low time counters. For example, if the post-scale divide factor is 10, the high and low count values are set to 5 and 5, to achieve a 50–50% duty cycle. The PLL implements this duty cycle by transitioning the output clock from high-to-low on the rising edge of the VCO output clock. However, a 4 and 6 setting for the high and low count values, respectively, would produce an output clock with a 40–60% duty cycle.

The `rselodd` bit indicates an odd divide factor for the VCO output frequency with a 50% duty cycle. For example, if the post-scale divide factor is three, the high and low time count values are 2 and 1, respectively, to achieve this division. This implies a 67%–33% duty cycle. If you need a 50%–50% duty cycle, you must set the `rselodd` control bit to 1 to achieve this duty cycle despite an odd division factor. The PLL implements this duty cycle by transitioning the output clock from high-to-low on a falling edge of the VCO output clock. When you set `rselodd` = 1, subtract 0.5 cycles from the high time and add 0.5 cycles to the low time.

For example:

- High time count = 2 cycles

Table 6–3. Cyclone IV Devices Supported I/O Standards and Constraints (Part 3 of 3)

I/O Standard	Type	Standard Support	V_{CCIO} Level (in V)		Column I/O Pins			Row I/O Pins (1)	
			Input	Output	CLK, DQS	PLL_OUT	User I/O Pins	CLK, DQS	User I/O Pins
LVPECL (7)	Differential	—	2.5	—	✓	—	—	✓	—

Notes to Table 6–3:

(1) Cyclone IV GX devices only support right I/O pins.

(2) The PCI-clamp diode must be enabled for 3.3-V/3.0-V LVTTL/LVCMOS.

(3) The Cyclone IV architecture supports the MultiVolt I/O interface feature that allows Cyclone IV devices in all packages to interface with I/O systems that have different supply voltages.

(4) Cyclone IV GX devices do not support 1.2-V V_{CCIO} in banks 3 and 9. I/O pins in bank 9 are dual-purpose I/O pins that are used as configuration or GPIO pins. Configuration scheme is not support at 1.2 V, therefore bank 9 can not be powered up at 1.2-V V_{CCIO}.

(5) Differential HSTL and SSTL outputs use two single-ended outputs with the second output programmed as inverted. Differential HSTL and SSTL inputs treat differential inputs as two single-ended HSTL and SSTL inputs and only decode one of them. Differential HSTL and SSTL are only supported on CLK pins.

(6) PPDS, mini-LVDS, and RSDS are only supported on output pins.

(7) LVPECL is only supported on clock inputs.

(8) Bus LVDS (BLVDS) output uses two single-ended outputs with the second output programmed as inverted. BLVDS input uses LVDS input buffer.

(9) 1.2-V HSTL input is supported at both column and row I/Os regardless of Class I or Class II.

(10) True LVDS, RSDS, and mini-LVDS I/O standards are supported in left and right I/O pins, while emulated LVDS, RSDS, and mini-LVDS I/O standards are supported in the top, bottom, and right I/O pins.

Cyclone IV devices support PCI and PCI-X I/O standards at 3.0-V V_{CCIO}. The 3.0-V PCI and PCI-X I/O are fully compatible for direct interfacing with 3.3-V PCI systems without requiring any additional components. The 3.0-V PCI and PCI-X outputs meet the V_{IH} and V_{IL} requirements of 3.3-V PCI and PCI-X inputs with sufficient noise margin.

For more information about the 3.3/3.0/2.5-V LVTTL & LVCMOS multivolt I/O support, refer to *AN 447: Interfacing Cyclone III and Cyclone IV Devices with 3.3/3.0/2.5-V LVTTL/LVCMOS I/O Systems*.

Termination Scheme for I/O Standards

This section describes recommended termination schemes for voltage-referenced and differential I/O standards.

The 3.3-V LVTTL, 3.0-V LVTTL and LVCMOS, 2.5-V LVTTL and LVCMOS, 1.8-V LVTTL and LVCMOS, 1.5-V LVCMOS, 1.2-V LVCMOS, 3.0-V PCI, and PCI-X I/O standards do not specify a recommended termination scheme per the JEDEC standard

Designing with LVDS

Cyclone IV I/O banks support the LVDS I/O standard. The Cyclone IV GX right I/O banks support true LVDS transmitters while the Cyclone IV E left and right I/O banks support true LVDS transmitters. On the top and bottom I/O banks, the emulated LVDS transmitters are supported using two single-ended output buffers with external resistors. One of the single-ended output buffers is programmed to have opposite polarity. The LVDS receiver requires an external 100-Ω termination resistor between the two signals at the input buffer.

Figure 6–12 shows a point-to-point LVDS interface using Cyclone IV devices true LVDS output and input buffers.

Figure 6–12. Cyclone IV Devices LVDS Interface with True Output Buffer on the Right I/O Banks

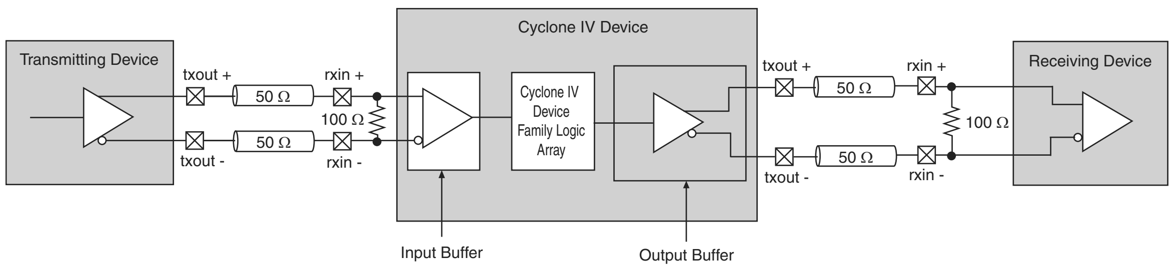
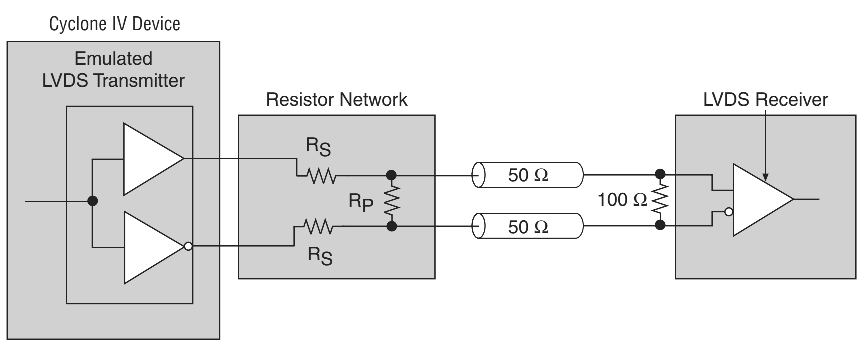


Figure 6–13 shows a point-to-point LVDS interface with Cyclone IV devices LVDS using two single-ended output buffers and external resistors.

Figure 6–13. LVDS Interface with External Resistor Network on the Top and Bottom I/O Banks *(1)*



Note to Figure 6–13:

(1) R_S = 120 Ω. R_P = 170 Ω.

BLVDS I/O Standard Support in Cyclone IV Devices

The BLVDS I/O standard is a high-speed differential data transmission technology that extends the benefits of standard point-to-point LVDS to multipoint configuration that supports bidirectional half-duplex communication. BLVDS differs from standard LVDS by providing a higher drive to achieve similar signal swings at the receiver while loaded with two terminations at both ends of the bus.

During device configuration, Cyclone IV E devices read configuration data using the parallel interface and configure their SRAM cells. This scheme is referred to as the AP configuration scheme because the device controls the configuration interface. This scheme contrasts with the FPP configuration scheme, where an external host controls the interface.

AP Configuration Supported Flash Memories

The AP configuration controller in Cyclone IV E devices is designed to interface with two industry-standard flash families—the Micron P30 Parallel NOR flash family and the Micron P33 Parallel NOR flash family. Unlike serial configuration devices, both of the flash families supported in AP configuration scheme are designed to interface with microprocessors. By configuring from an industry standard microprocessor flash which allows access to the flash after entering user mode, the AP configuration scheme allows you to combine configuration data and user data (microprocessor boot code) on the same flash memory.

The Micron P30 flash family and the P33 flash family support a continuous synchronous burst read mode at 40 MHz `DCLK` frequency for reading data from the flash. Additionally, the Micron P30 and P33 flash families have identical pin-out and adopt similar protocols for data access.

☞ Cyclone IV E devices use a 40-MHz oscillator for the AP configuration scheme. The oscillator is the same oscillator used in the Cyclone IV E AS configuration scheme.

Table 8–10 lists the supported families of the commodity parallel flash for the AP configuration scheme.

Table 8–10. Supported Commodity Flash for AP Configuration Scheme for Cyclone IV E Devices (1)

Flash Memory Density	Micron P30 Flash Family (2)	Micron P33 Flash Family (3)
64 Mbit	✓	✓
128 Mbit	✓	✓
256 Mbit	✓	✓

Notes to Table 8–10:

(1) The AP configuration scheme only supports flash memory speed grades of 40 MHz and above.

(2) 3.3- , 3.0-, 2.5-, and 1.8-V I/O options are supported for the Micron P30 flash family.

(3) 3.3-, 3.0- and 2.5-V I/O options are supported for the Micron P33 flash family.

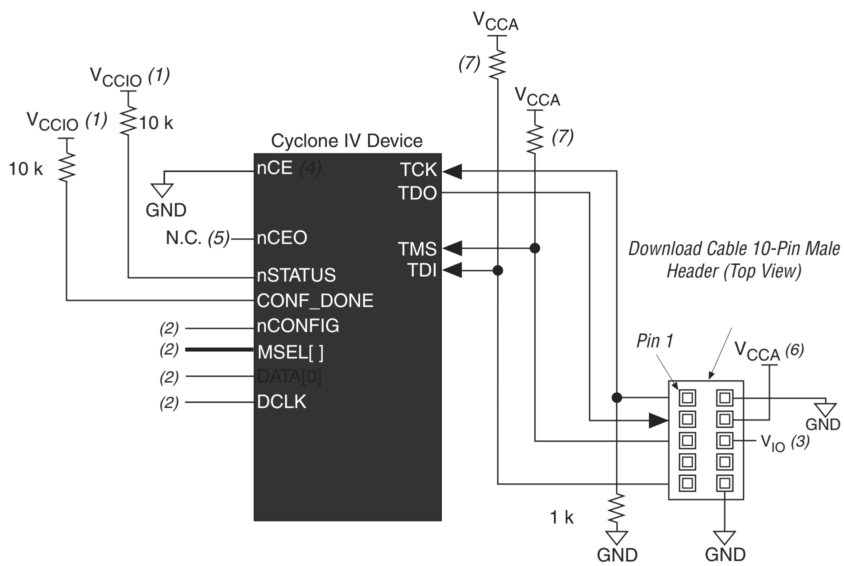
Configuring Cyclone IV E devices from the Micron P30 and P33 family 512-Mbit flash memory is possible, but you must properly drive the extra address and `FLASH_nCE` pins as required by these flash memories.

To check for supported speed grades and package options, refer to the respective flash datasheets.

The AP configuration scheme in Cyclone IV E devices supports flash speed grades of 40 MHz and above. However, AP configuration for all these speed grades must be capped at 40 MHz. The advantage of faster speed grades is realized when your design in the Cyclone IV E devices accesses flash memory in user mode.

For device using V_{CCIO} of 2.5, 3.0, and 3.3 V, refer to Figure 8–23. All I/O inputs must maintain a maximum AC voltage of 4.1 V because JTAG pins do not have the internal PCI clamping diodes to prevent voltage overshoot when using V_{CCIO} of 2.5, 3.0, and 3.3 V. You must power up the V_{CC} of the download cable with a 2.5-V supply from V_{CCA}. For device using V_{CCIO} of 1.2, 1.5, and 1.8 V, refer to Figure 8–24. You can power up the V_{CC} of the download cable with the supply from V_{CCIO}.

Figure 8–23. JTAG Configuration of a Single Device Using a Download Cable (2.5, 3.0, and 3.3-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8–23:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the `nCONFIG` and `MSEL` pins to support a non-JTAG configuration scheme. If you only use JTAG configuration, connect the `nCONFIG` pin to logic-high and the `MSEL` pins to GND. In addition, pull `DCLK` and `DATA[0]` to either high or low, whichever is convenient on your board.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} must match the device's V_{CCA}. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the USB-Blaster, ByteBlaster II, ByteBlasterMV, and EthernetBlaster cables, this pin is a no connect.

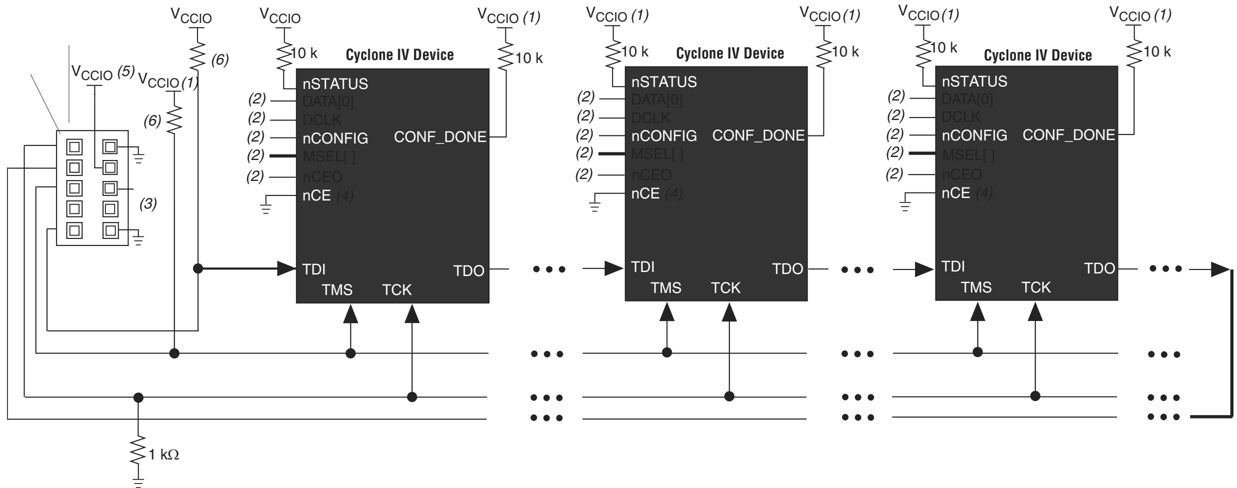
(4) The `nCE` pin must be connected to GND or driven low for successful JTAG configuration.

(5) The `nCEO` pin is left unconnected or used as a user I/O pin when it does not feed the `nCE` pin of another device.

(6) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

(7) Resistor value can vary from 1 kΩ to 10 kΩ..

Figure 8–26. JTAG Configuration of Multiple Devices Using a Download Cable (1.2, 1.5, and 1.8-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8–26:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the nCONFIG and MSEL pins to support a non-JTAG configuration scheme. If you only use a JTAG configuration, connect the nCONFIG pin to logic-high and the MSEL pins to GND. In addition, pull DCLK and DATA[0] to either high or low, whichever is convenient on your board.

(3) In the USB-Blaster and ByteBlaster II cable, this pin is connected to nCE when it is used for AS programming, otherwise it is a no connect.

(4) You must connect the nCE pin to GND or driven low for successful JTAG configuration.

(5) Power up the V_{CC} of the ByteBlaster II or USB-Blaster cable with supply from V_{CCIO}. The ByteBlaster II and USB-Blaster cables do not support a target supply voltage of 1.2 V. For the target supply voltage value, refer to the *ByteBlaster II Download Cable User Guide* and the *USB-Blaster Download Cable User Guide*.

(6) Resistor value can vary from 1 kΩ to 10 kΩ.

If a non-Cyclone IV device is cascaded in the JTAG-chain, TDO of the non-Cyclone IV device driving into TDI of the Cyclone IV device must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

The CONF_DONE and nSTATUS signals are shared in multi-device AS, AP, PS, and FPP configuration chains to ensure that the devices enter user mode at the same time after configuration is complete. When the CONF_DONE and nSTATUS signals are shared among all the devices, you must configure every device when JTAG configuration is performed.

If you only use JTAG configuration, Altera recommends that you connect the circuitry as shown in Figure 8–25 or Figure 8–26, in which each of the CONF_DONE and nSTATUS signals are isolated so that each device can enter user mode individually.

After the first device completes configuration in a multi-device configuration chain, its nCEO pin drives low to activate the nCE pin of the second device, which prompts the second device to begin configuration. Therefore, if these devices are also in a JTAG chain, ensure that the nCE pins are connected to GND during JTAG configuration or that the devices are JTAG configured in the same order as the configuration chain. As long as the devices are JTAG configured in the same order as the multi-device configuration chain, the nCEO of the previous device drives the nCE pin of the next device low when it has successfully been JTAG configured. You can place other Altera devices that have JTAG support in the same JTAG chain for device programming and configuration.

Use the ACTIVE_DISENGAGE instruction with the CONFIG_IO instruction to interrupt configuration. Table 8–16 lists the sequence of instructions to use for various CONFIG_IO usage scenarios.

Table 8–16. JTAG CONFIG_IO (without JTAG_PROGRAM) Instruction Flows *(1)*

<table>
<tr><th rowspan="3">JTAG Instruction</th><th colspan="12">Configuration Scheme and Current State of the Cyclone IV Device</th></tr>
<tr><th colspan="4">Prior to User Mode (Interrupting Configuration)</th><th colspan="4">User Mode</th><th colspan="4">Power Up</th></tr>
<tr><th>PS</th><th>FPP</th><th>AS</th><th>AP</th><th>PS</th><th>FPP</th><th>AS</th><th>AP</th><th>PS</th><th>FPP</th><th>AS</th><th>AP</th></tr>
<tr><td>ACTIVE_DISENGAGE</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>CONFIG_IO</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>NA</td><td>NA</td><td>NA</td><td>NA</td></tr>
<tr><td>JTAG Boundary Scan Instructions (no JTAG_PROGRAM)</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>O</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>ACTIVE_ENGAGE</td><td rowspan="3">A</td><td rowspan="3">A</td><td>R (2)</td><td>R (2)</td><td rowspan="3">A</td><td rowspan="3">A</td><td>R (2)</td><td>R (2)</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>PULSE_NCONFIG</td><td>A (3)</td><td>A (3)</td><td>O</td><td>O</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>Pulse nCONFIG pin</td><td>A (3)</td><td>A (3)</td><td>O</td><td>O</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
<tr><td>JTAG TAP Reset</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>R</td><td>—</td><td>—</td><td>—</td><td>—</td></tr>
</table>

Notes to Table 8–16:

(1) You must execute "R" indicates that the instruction before the next instruction, "O" indicates the optional instruction, "A" indicates that the instruction must be executed, and "NA" indicates that the instruction is not allowed in this mode.

(2) Required if you use ACTIVE_DISENGAGE.

(3) Neither of the instruction is required if you use ACTIVE_ENGAGE.

The CONFIG_IO instruction does not hold nSTATUS low until reconfiguration. You must disengage the AS or AP configuration controller by issuing the ACTIVE_DISENGAGE and ACTIVE_ENGAGE instructions when active configuration is interrupted. You must issue the ACTIVE_DISENGAGE instruction alone or prior to the CONFIG_IO instruction if the JTAG_PROGRAM instruction is to be issued later (Table 8–17). This puts the active configuration controllers into the idle state. The active configuration controller is re-engaged after user mode is reached through JTAG programming (Table 8–17).

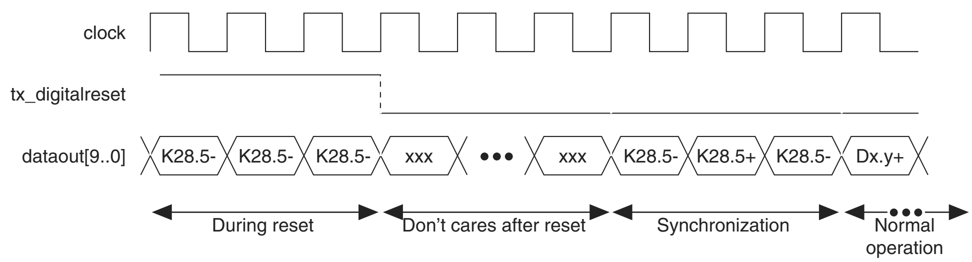
☞ While executing the CONFIG_IO instruction, all user I/Os are tri-stated.

If reconfiguration after interruption is performed using configuration modes (rather than using JTAG_PROGRAM), it is not necessary to issue the ACTIVE_DISENGAGE instruction prior to CONFIG_IO. You can start reconfiguration by either pulling nCONFIG low for at least 500 ns or issuing the PULSE_NCONFIG instruction. If the ACTIVE_DISENGAGE instruction was issued and the JTAG_PROGRAM instruction fails to enter user mode, you must issue the ACTIVE_ENGAGE instruction to reactivate the active configuration controller. Issuing the ACTIVE_ENGAGE instruction also triggers reconfiguration in configuration modes; therefore, it is not necessary to pull nCONFIG low or issue the PULSE_NCONFIG instruction.

The following describes the 8B/10B encoder behavior in reset condition (as shown in Figure 1–7):

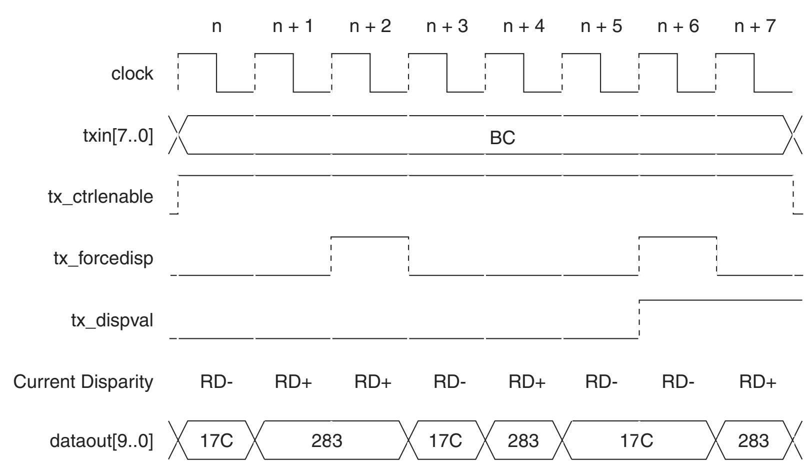
- During reset, the 8B/10B encoder ignores the inputs (`tx_datain` and `tx_ctrlenable` ports) from the FPGA fabric and outputs the K28.5 pattern from the RD- column continuously until the `tx_digitalreset` port is deasserted.
- Upon deassertion of the `tx_digitalreset` port, the 8B/10B encoder starts with a negative disparity and transmits three K28.5 code groups for synchronization before it starts encoding and transmitting data on its output.
- Due to some pipelining of the transmitter PCS, some "don't cares" (10'hxxx) are sent before the three synchronizing K28.5 code groups.

Figure 1–7. 8B/10B Encoder Behavior in Reset Condition



The encoder supports forcing the running disparity to either positive or negative disparity with `tx_forcedisp` and `tx_dispval` ports. Figure 1–8 shows an example of `tx_forcedisp` and `tx_dispval` port use, where data is shown in hexadecimal radix.

Figure 1–8. Force Running Disparity Operation

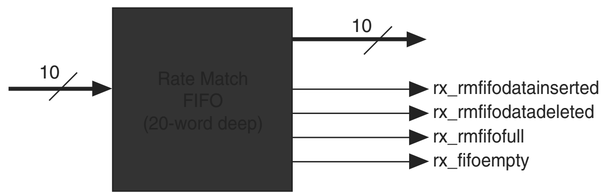


In this example, a series of K28.5 code groups are continuously sent. The stream alternates between a positive disparity K28.5 (RD+) and a negative disparity K28.5 (RD-) to maintain a neutral overall disparity. The current running disparity at time $n + 1$ indicates that the K28.5 in time $n + 2$ should be encoded with a negative disparity. Because `tx_forcedisp` is high at time $n + 2$, and `tx_dispval` is low, the K28.5

Rate Match FIFO

In asynchronous systems, the upstream transmitter and local receiver can be clocked with independent reference clocks. Frequency differences in the order of a few hundred ppm can corrupt the data when latching from the recovered clock domain (the same clock domain as the upstream transmitter reference clock) to the local receiver reference clock domain. Figure 1–21 shows the rate match FIFO block diagram.

Figure 1–21. Rate Match FIFO Block Diagram



The rate match FIFO compensates for small clock frequency differences of up to ±300 ppm (600 ppm total) between the upstream transmitter and the local receiver clocks by performing the following functions:

- Insert skip symbols when the local receiver reference clock frequency is greater than the upstream transmitter reference clock frequency
- Delete skip symbols when the local receiver reference clock frequency is less than the upstream transmitter reference clock frequency

The 20-word deep rate match FIFO and logics control insertion and deletion of skip symbols, depending on the ppm difference. The operation begins after the word aligner synchronization status (`rx_syncstatus`) is asserted.

☞ Rate match FIFO is only supported with 8B/10B encoded data and the word aligner in automatic synchronization state machine mode.

8B/10B Decoder

The 8B/10B decoder receives 10-bit data and decodes it into an 8-bit data and a 1-bit control identifier. The decoder is compliant with Clause 36 of the IEEE 802.3 specification.

Figure 1–22 shows the 8B/10B decoder block diagram.

Figure 1–22. 8B/10B Decoder Block Diagram

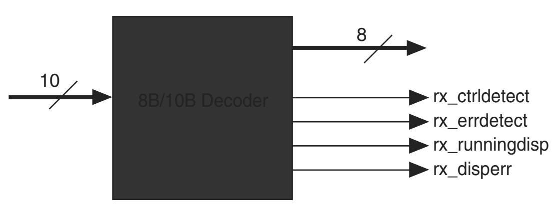


Figure 1–35 shows the datapath clocking in the transmitter and receiver operation mode with the rate match FIFO. The receiver datapath clocking in configuration without the rate match FIFO is identical to Figure 1–34.

In configuration with the rate match FIFO, the CDR unit in the receiver channel recovers the clock from received serial data and generates the high-speed recovered clock for the deserializer, and low-speed recovered clock for forwarding to the receiver PCS. The low-speed recovered clock feeds to the following blocks in the receiver PCS:

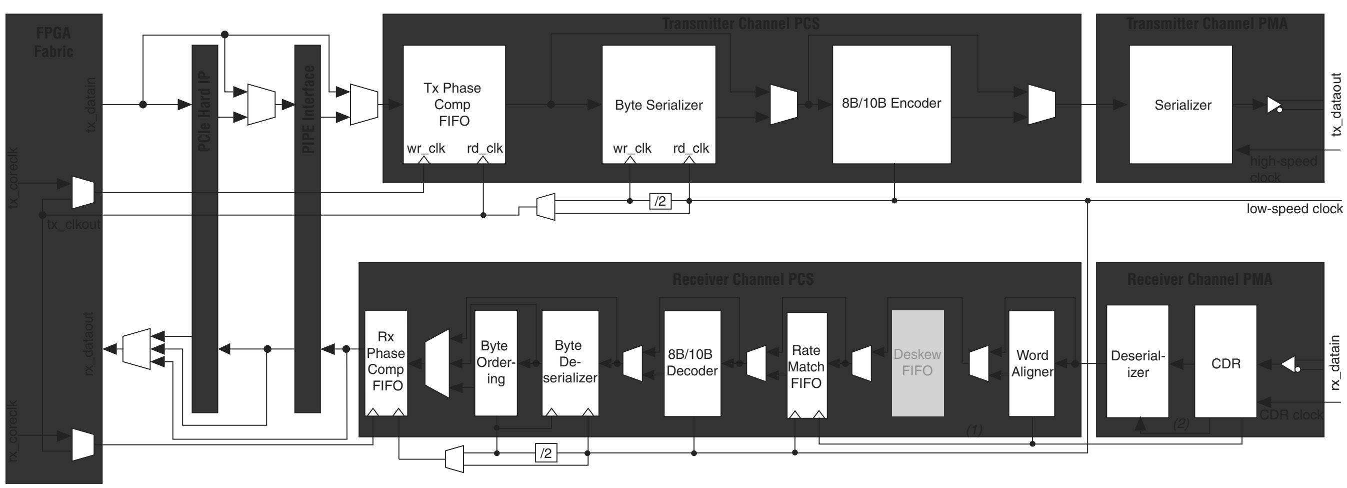
- word aligner
- write clock of rate match FIFO

The low-speed clock that is used in the transmitter PCS datapath feeds the following blocks in the receiver PCS:

- read clock of rate match FIFO
- 8B/10B decoder
- write clock of byte deserializer
- byte ordering
- write clock of RX phase compensation FIFO

When the byte deserializer is enabled, the low-speed clock frequency is halved before feeding into the write clock of RX phase compensation FIFO. The low-speed clock is available in the FPGA fabric as `tx_clkout` port, which can be used in the FPGA fabric to send transmitter data and control signals, and capture receiver data and status signals.

Figure 1–35. Transmitter and Receiver Datapath Clocking with Rate Match FIFO in Non-Bonded Channel Configuration



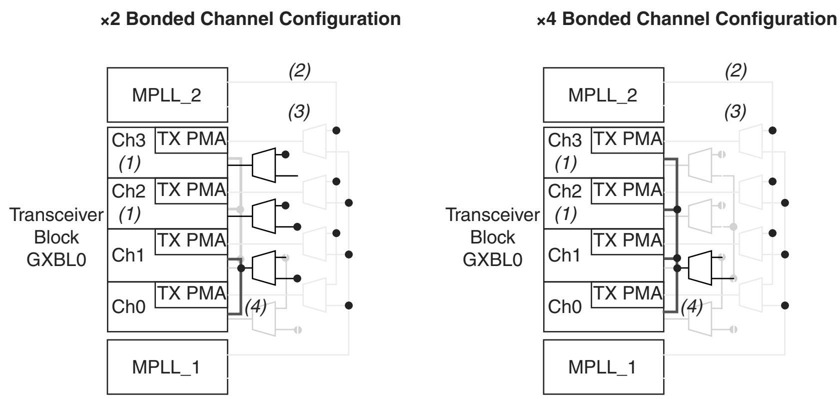
Notes to Figure 1–35:

(1) Low-speed recovered clock.

(2) High-speed recovered clock.

Figure 1–36 and Figure 1–37 show the independent high-speed clock and bonded low-speed clock distributions for transceivers in F324 and smaller packages, and in F484 and larger packages in bonded (×2 and ×4) channel configuration.

Figure 1–36. Clock Distribution in Bonded (×2 and ×4) Channel Configuration for Transceivers in F324 and Smaller Packages.



Notes to Figure 1–36:

(1) Transceiver channels 2 and 3 are not available for devices in F169 and smaller packages.

(2) High-speed clock.

(3) Low-speed clock.

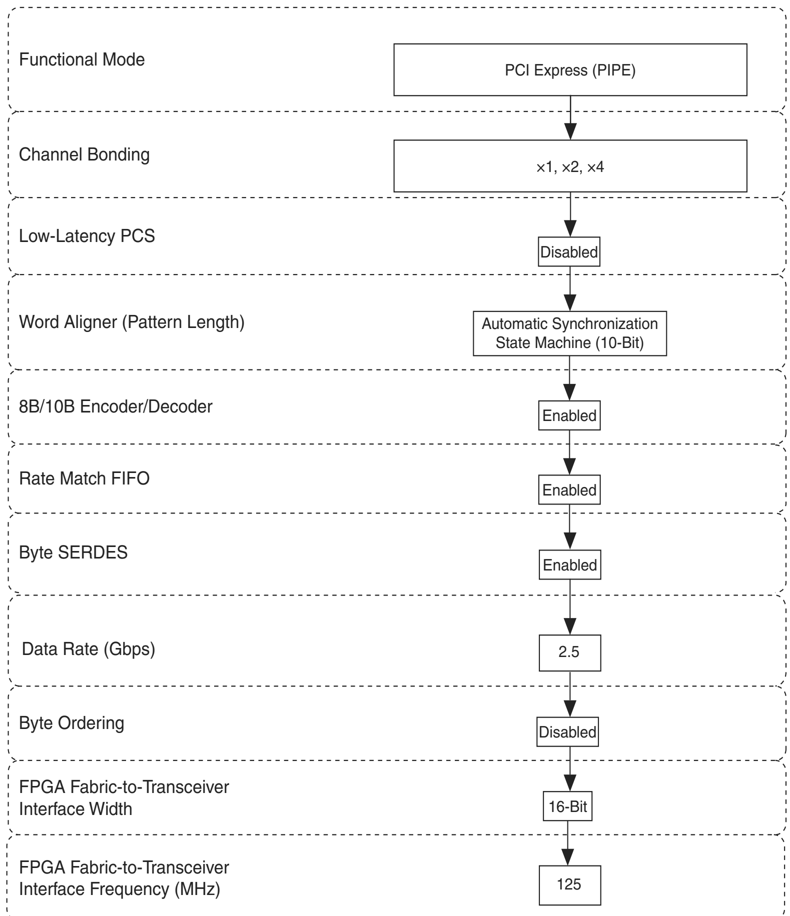
(4) Bonded common low-speed clock path.

Configuring the hard IP module requires using the PCI Express Compiler. When configuring the transceiver for PCIe implementation with hard IP module, the byte serializer and deserializer are not enabled, providing an 8-bit transceiver-PIPE-hard IP data interface width running at 250 MHz clock frequency.

For more information about PCIe implementation with hard IP module, refer to the *PCI Express Compiler User Guide*.

Figure 1–49 shows the transceiver configuration in PIPE mode.

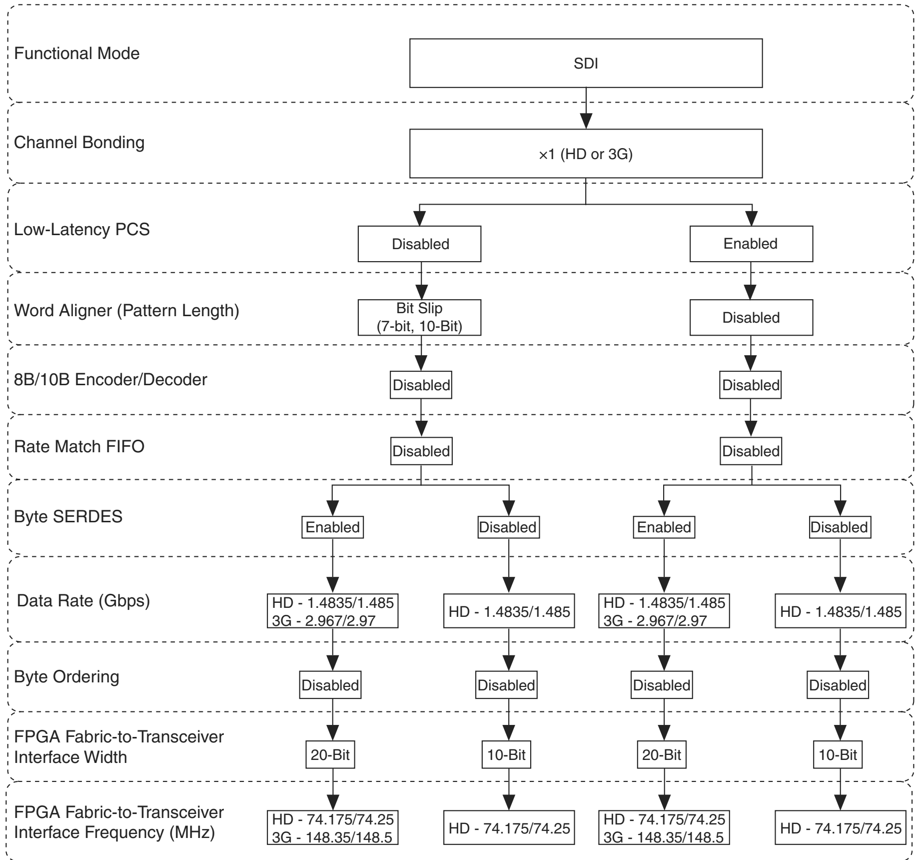
Figure 1–49. Transceiver Configuration in PIPE Mode



When configuring the transceiver into PIPE mode using ALTGX megafunction for PCIe implementation, the PHY-MAC, data link and transaction layers must be implemented in user logics. The PCIe hard IP block is bypassed in this configuration.

Figure 1–69 shows the transceiver configuration in SDI mode.

Figure 1–69. Transceiver Configuration in SDI Mode



Altera recommends driving `rx_bitslip` port low in configuration where low-latency PCS is not enabled. In SDI systems, the word alignment and framing occurs after descrambling, which is implemented in the user logic. The word alignment therefore is not useful, and keeping `rx_bitslip` port low avoids the word aligner from inserting bits in the received data stream.

Loopback

Cyclone IV GX devices provide three loopback options that allow you to verify the operation of different functional blocks in the transceiver channel. The following loopback modes are available:

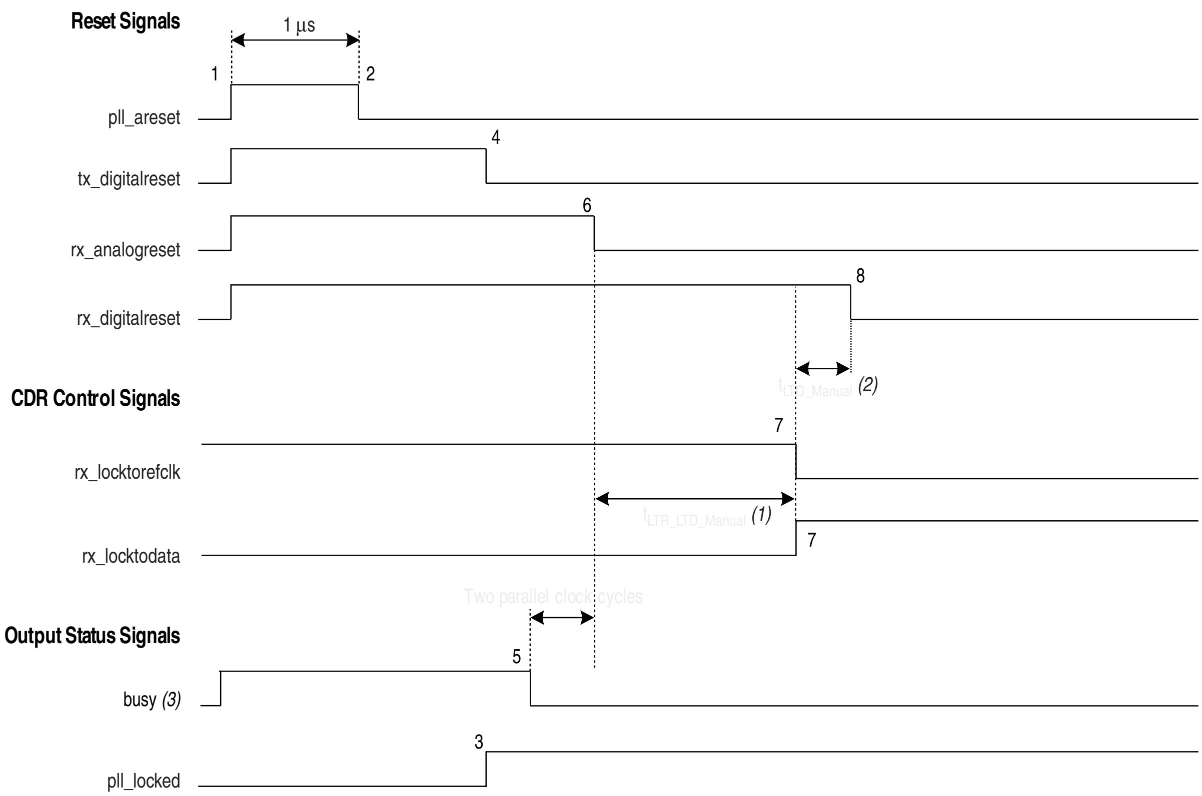
- reverse parallel loopback (available only for PIPE mode)
- serial loopback (available for all modes except PIPE mode)
- reverse serial loopback (available for all modes except XAUI mode)

In each loopback mode, all transmitter buffer and receiver buffer settings are available if the buffers are active, unless stated otherwise.

Receiver and Transmitter Channel—Receiver CDR in Manual Lock Mode

This configuration contains both a transmitter and receiver channel. If you create a **Receiver and Transmitter** instance in the ALTGX MegaWizard Plug-In Manager with the receiver CDR in manual lock mode, use the reset sequence shown in Figure 2–9.

Figure 2–9. Sample Reset Sequence of Receiver and Transmitter Channel—Receiver CDR in Manual Lock Mode



Notes to Figure 2–9:

(1) For $t_{LTR\_LTD\_Manual}$ duration, refer to the *Cyclone IV Device Datasheet* chapter.

(2) For t_{LTD_Manual} duration, refer to the *Cyclone IV Device Datasheet* chapter.

(3) The `busy` signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the `busy` signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

As shown in Figure 2–9, perform the following reset procedure for the receiver in manual lock mode:

1. After power up, assert `pll_areset` for a minimum period of 1 µs (the time between markers 1 and 2).
2. Keep the `tx_digitalreset`, `rx_analogreset`, `rx_digitalreset`, and `rx_locktorefclk` signals asserted and the `rx_locktodata` signal deasserted during this time period. After you deassert the `pll_areset` signal, the multipurpose PLL starts locking to the transmitter input reference clock.
3. After the multipurpose PLL locks, as indicated by the `pll_locked` signal going high (marker 3), deassert `tx_digitalreset` (marker 4). For receiver operation, after deassertion of busy signal (marker 5), wait for two parallel clock cycles to deassert the `rx_analogreset` signal (marker 6). After `rx_analogreset` deassert, `rx_pll_locked` will assert.

Chapter Revision Dates

The chapters in this document, Cyclone IV Device Handbook, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

Chapter 1. Cyclone IV Device Datasheet
Revised: *December 2016*
Part Number: *CYIV-53001-2.1*